

Data sheet acquired from Harris Semiconductor SCHS206B

February 1998 - Revised May 2003

High-Speed CMOS Logic CMOS Programmable Divide-by-N Counter

Features

- Synchronous Programmable ÷N Counter N = 3 to 9999 or 15999
- Presettable Down-Counter
- Fully Static Operation
- Mode-Select Control of Initial Decade Counting Function (÷10, 8, 5, 4, 2)
- · Master Preset Initialization
- · Latchable +N Output
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V

Applications

- Communications Digital Frequency Synthesizers;
 VHF, UHF, FM, AM, etc.
- Fixed or Programmable Frequency Division
- "Time Out" Timer for Consumer-Application Industrial Controls

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4059F3A	-55 to 125	24 Ld CERDIP
CD74HC4059E	-55 to 125	24 Ld PDIP
CD74HC4059M96	-55 to 125	24 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel.

Description

The 'HC4059 are high-speed silicon-gate devices that are pin-compatible with the CD4059A devices of the CD4000B series. These devices are divide-by-N down-counters that can be programmed to divide an input frequency by any number "N" from 3 to 15,999. The output signal is a pulse one clock cycle wide occurring at a rate equal to the input frequency divide by N. The down-counter is preset by means of 16 jam inputs.

The three Mode-Select Inputs K_a , K_b and K_c determine the modulus ("divide-by" number) of the first and last counting sections in accordance with the truth table. Every time the first (fastest) counting section goes through one cycle, it reduces by 1 the number that has been preset (jammed) into the three decades of the intermediate counting section an the last counting section, which consists of flip-flops that are not needed for opening the first counting section. For example, in the ÷2 mode, only one flip-flop is needed in the first counting section. Therefore the last counting section has three flip-flops that can be preset to a maximum count of seven with a place value of thousands. If ÷10 is desired for the first section, K_a is set "high", K_b "high" and K_c "low". Jam inputs J1, J2, J3, and J4 are used to preset the first counting section and there is no last counting section. The intermediate counting section consists of three cascaded BCD decade (÷10) counters presettable by means of Jam Inputs J5 through J16.

The Mode-Select Inputs permit frequency-synthesizer channel separations of 10, 12.5, 20, 25 or 50 parts. These inputs set the maximum value of N at 9999 (when the first counting section divides by 5 or 10) or 15,999 (when the first counting section divides by 8, 4, or 2).

The three decades of the intermediate counter can be preset to a binary 15 instead of a binary 9, while their place values are still 1, 10, and 100, multiplied by the number of the ÷N mode. For example, in the ÷8 mode, the number from which counting down begins can be preset to:

3rd Decade	1500
2nd Decade	150
1st Decade	15
Last Counting Section	1000

The total of these numbers (2665) times 8 equals 12,320. The first counting section can be preset to 7. Therefore, 21,327 is the maximum possible count in the $\div 8$ mode.

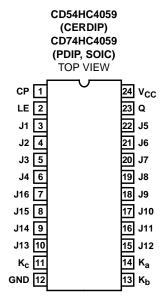
The highest count of the various modes is shown in the Extended Counter Range column. Control inputs K_{b} and K_{c} can be used to initiate and lock the counter in the "master preset" state. In this condition the flip-flops in the counter are preset in accordance with the jam inputs and the counter remains in that state as long as K_{b} and K_{c} both remain low. The counter begins to count down from the preset state when a counting mode other than the master preset mode is selected.

The counter should always be put in the master preset mode before the $\div 5$ mode is selected. Whenever the master preset mode is used, control signals K_b = "low" and K_c = "low" must be applied for at least 3 full clock pulses.

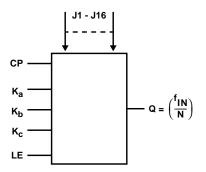
After Preset Mode inputs have been changed to one of the ÷ modes, the next positive-going clock transition changes an internal flip-flop so that the countdown can begin at the second positive-going clock transition. Thus, after an MP (Master Preset) mode, there is always one extra count before the output goes high. Figure 1 illustrates a total count of 3 (÷8 mode). If the Master Preset mode is started two clock cycles or less before an output pulse, the output pulse will appear at the time due. If the Master Preset Mode is not used, the counter jumps back to the "Jam" count when the output pulse appears.

A "high" on the Latch Enable input will cause the counter output to remain high once an output pulse occurs, and to remain in the high state until the latch input returns to "low". If the Latch Enable is "low", the output pulse will remain high for only one cycle of the clock-input signal.

Pinout



Functional Diagram



TRUTH TABLE

								COUNTER RANGE		
MODE SELECT INPUT FIRST COUNTING SECTION				ECTION	LAST C	OUNTING SE	ECTION	DESIGN	EXTENDED	
K _a	К _b	K _c	MODE DIVIDES-BY	CAN BE PRESET TO A MAX OF:	(NOTE 1) JAM INPUTS USED:	MODE DIVIDES-BY	CAN BE PRESET TO A MAX OF:	(NOTE 1) JAM INPUTS USED:	MAX	MAX
Н	Н	Н	2	1	J1	8	7	J2, J3, J4	15,999	17,331
L	Н	Н	4	3	J1, J2	4	3	J3, J4	15,999	18,663
Н	L	Н	5 (Note 2)	4	J1, J2, J3	2	1	J4	9,999	13,329
L	L	Н	8	7	J1, J2, J3	2	1	J4	15,999	21,327
Н	Н	L	10	9	J1, J2, J3, J4	1	0	-	9,999	16,659
Х	L	L		Master Prese	t		Master Prese	=	-	

X = Don't care

NOTES:

- 1. J1 = Least Significant Bit. J4 = Most Significant Bit.
- 2. Operation in the 5mode (1st counting section) requires going through the Master Preset mode prior to going into the 5mode. At power turn-on, Kc must be "low" for a period of 3 input clock pulses after VCC reaches a minimum of 3V.

How to Preset the HC/HCT4059 to Desired ÷N

The value N is determined as follows:

(EQ. 1)

Preset Value = $\frac{N}{\text{Mode}}$ (EQ. 2)

N = (MODE†) (1000 x Decade 5 Preset + 100 x Decade 4 Preset + 10 x Decade 3 Preset + 1 x Decade 2 Preset) + Decade 1 Preset

Example:

Mode Select = 5

† MODE = First counting section divider (10, 8, 5, 4 or 2)

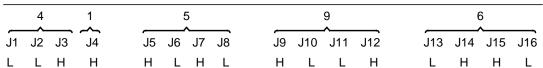
N = 8479, Mode = 5

K_a K_b K_c H L H

To calculate preset values for any N count, divide the N count by the Mode. The resultant is the corresponding preset values of the 5th through 2nd decade with the remainder being equal to the 1st decade value.

1695 + 4 (Preset Values) 5 | 8479

Program Jam Inputs (BCD)



NOTE: To verify the results, use Equation 1: $N = 5 (1000 \times 1 + 100 \times 6 + 10 \times 9 + 1 \times 5) + 4$

N = 8479

PROGRAM JAM INPUTS (BCD)

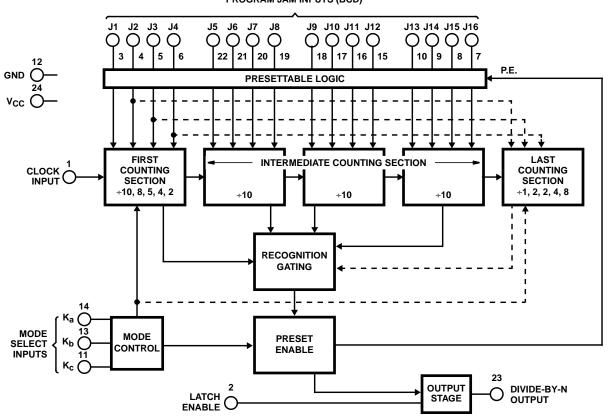


FIGURE 1. FUNCTIONAL BLOCK DIAGRAM

Absolute Maximum Ratings

DC Supply Voltage, V _{CC} 0.5V to 7V
DC Input Diode Current, I _{IK}
For $V_1 < -0.5V$ or $V_1 > V_{CC} + 0.5V \dots \pm 20$ mA
DC Output Diode Current, I _{OK}
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ ±25mA
DC V _{CC} or Ground Current, I _{CC}

Thermal Information

Thermal Resistance (Typical)	θ_{JA} (°C/W)
E (PDIP) Package (Note 3)	67
M (SOIC) Package (Note 4)	
Maximum Junction Temperature (Hermetic Package or	Die) 175 ⁰ C
Maximum Junction Temperature (Plastic Package)	150 ^o C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300 ^o C

Operating Conditions

Temperature Range, T _A	55°C to 125°C
Supply Voltage Range, VCC	2V to 6V
DC Input or Output Voltage, V _I , V _O	0V to V _{CC}
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- 3. The package thermal impedance is calculated in accordance with JESD 51-3.
- 4. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

		TEST CONDITIONS		v _{cc}	25°C			-40°C 1	O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	1	-	3.15	-	3.15	-	V
				6	4.2	1	-	4.2	-	4.2	-	V
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	٧
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output	V _{OH}	V _{IH} or	-0.02	2	1.9	-	-	1.9	-	1.9	-	٧
Voltage CMOS Loads		V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output			-	-	-	-	-	-	-	-	-	٧
Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	٧
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	٧
Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	٧
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output	1		-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
TTE Education			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	II	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μΑ
Quiescent Device Current	Icc	V _{CC} or GND	0	6	-	1	8	-	80	-	160	μА

Prerequisite for Switching Specifications

			25°C			-40	°C TO 8	5°C	-55°C TO 125°C			
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Pulse Width CP	t _W	2	90	-	-	115	-	-	135	-	-	ns
		4.5	18	-	-	23	-	-	27	-	-	ns
		6	15	-	-	20	-	-	23	-	-	ns
Setup Time	tsu	2	75	-	-	95	-	-	110	-	-	ns
K _b , K _c to CP		4.5	15	-	-	19	-	-	22	-	-	ns
		6	13	-	-	16	-	-	19	-	-	ns
CP Frequency	f _{MAX}	2	5	-	-	4	-	-	4	-	-	MHz
		4.5	27	-	-	22	-	-	18	-	-	MHz
		6	32	-	-	26	-	-	21	-	-	MHz

Switching Specifications Input t_{r} , $t_{f} = 6$ ns

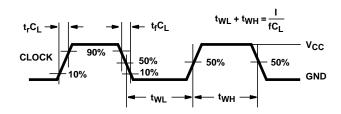
		TEST CONDITIONS	v _{cc}	25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL		(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	200	-	250	-	300	ns
CP to Q			4.5	-	-	40	-	50	-	60	ns
			6	-	-	34	-	43	-	51	ns
		C _L = 15pF	5	-	17	-	-	-	-	-	ns
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	175	-	220	-	265	ns
LE to Q			4.5	-	-	35	-	44	-	53	ns
			6	-	-	30	-	37	-	45	ns
		C _L = 15pF	5	-	14	-	-	-	-	-	ns
Output Transition Time	t _{THL} , t _{TLH}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
CP Frequency	f _{MAX}	C _L = 15pF	5	-	54	-	-	-	-	-	MHz
Input Capacitance	Cl	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 5, 6)	C _{PD}	-	5	-	36	-	-	-	-	-	pF

NOTES:

^{5.} $C_{\mbox{\scriptsize PD}}$ is used to determine the dynamic power consumption, per package.

^{6.} $P_D = C_{PD} V_{CC}^2 f_i + \Sigma C_L V_{CC}^2 f_o$ where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, V_{CC} = supply voltage.

Test Circuits and Waveforms



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX} , input duty cycle = 50%.

FIGURE 2. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

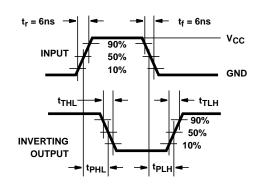


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

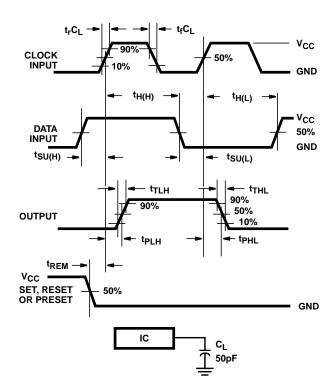


FIGURE 4. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

0.571(14,50)

0.514(13,06)

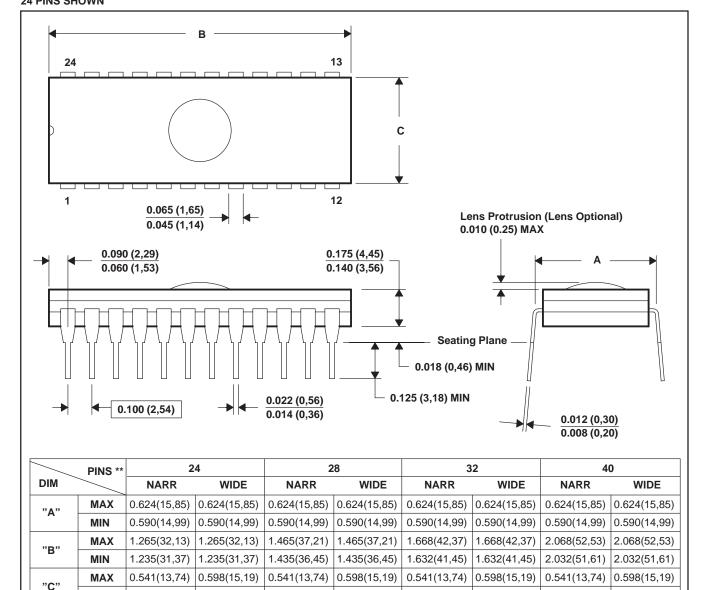
0.514(13,06) 0.571(14,50)

4040084/C 10/97

J (R-GDIP-T**)

24 PINS SHOWN

CERAMIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

0.514(13,06)

MIN

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).

0.571(14,50)

D. This package can be hermetically sealed with a ceramic lid using glass frit.

0.514(13,06)

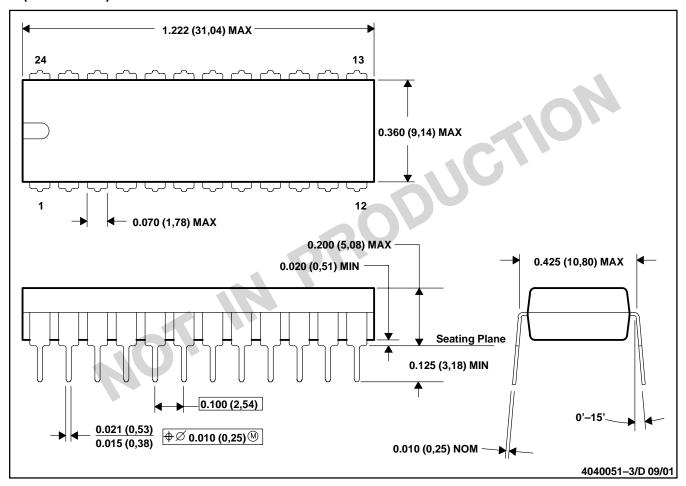
E. Index point is provided on cap for terminal identification.



0.571(14,50)

N (R-PDIP-T24)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

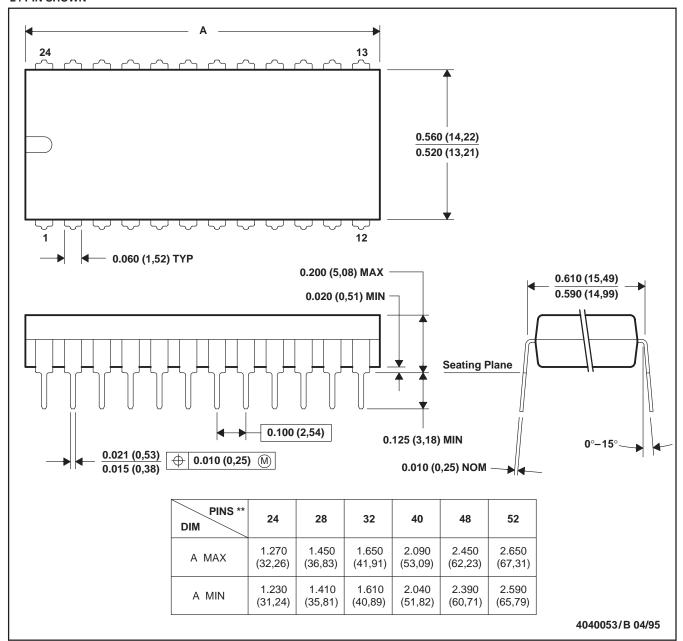
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-010

1

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-011

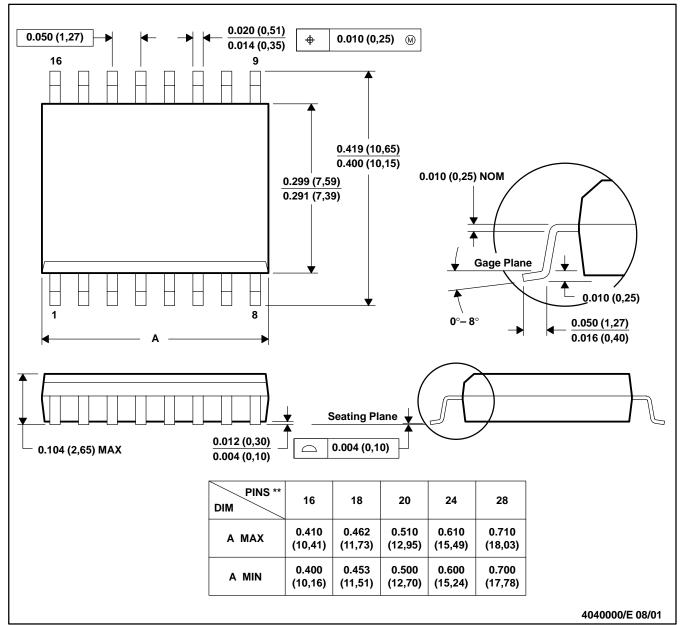
D. Falls within JEDEC MS-015 (32 pin only)



DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265

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